Product End-of-Life Disassembly Instructions

Product Category: Notebooks and Tablet PCs

Marketing Name / Model
[List multiple models if applicable.]

HP EliteBook 8540w Mobile Workstation

Name / Model #2
Name / Model #3
Name / Model #4
Name / Model #5

Purpose: The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HP products to remove components and materials requiring selective treatment, as defined by EU directive 2002/96/EC, Waste Electrical and Electronic Equipment (WEEE).

1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.
1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

<table>
<thead>
<tr>
<th>Item Description</th>
<th>Notes</th>
<th>Quantity of items included in product</th>
</tr>
</thead>
<tbody>
<tr>
<td>Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)</td>
<td>With a surface greater than 10 sq cm Mother board</td>
<td>1</td>
</tr>
<tr>
<td>Batteries</td>
<td>All types including standard alkaline and lithium coin or button style batteries battery and RTC battery</td>
<td>2</td>
</tr>
<tr>
<td>Mercury-containing components</td>
<td>For example, mercury in lamps, display backlights, scanner lamps, switches, batteries</td>
<td></td>
</tr>
<tr>
<td>Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm</td>
<td>Includes background illuminated displays with gas discharge lamps LCD</td>
<td>1</td>
</tr>
<tr>
<td>Cathode Ray Tubes (CRT)</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Capacitors / condensers (Containing PCB/PCT)</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height</td>
<td></td>
<td></td>
</tr>
<tr>
<td>External electrical cables and cords</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Gas Discharge Lamps</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Plastics containing Brominated Flame Retardants</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner</td>
<td>Include the cartridges, print heads, tubes, vent chambers, and service stations.</td>
<td></td>
</tr>
<tr>
<td>Components and waste containing asbestos</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Components, parts and materials containing refractory ceramic fibers</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Components, parts and materials containing radioactive substances</td>
<td></td>
<td></td>
</tr>
</tbody>
</table>
2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

<table>
<thead>
<tr>
<th>Tool Description</th>
<th>Tool Size (if applicable)</th>
</tr>
</thead>
<tbody>
<tr>
<td>Description #1 screw driver</td>
<td>philip #1 / TORX T8</td>
</tr>
<tr>
<td>Description #2</td>
<td></td>
</tr>
<tr>
<td>Description #3</td>
<td></td>
</tr>
<tr>
<td>Description #4</td>
<td></td>
</tr>
<tr>
<td>Description #5</td>
<td></td>
</tr>
</tbody>
</table>

3.0 Product Disassembly Process

3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment:

1. Remove Battery module
2. Remove Mini card door
3. Remove Ram door and RTC battery.
4. Remove Blue tooth door.
5. Remove HDD door.
6. Remove HDD module
7. Remove ODD assembly
8. Remove Keyboard
9. Remove strip cover (with power button PCB & caps lock PCB)
10. Remove LCD cable and antenna connector
11. Divide LCD assembly from base assembly
12. Remove fan module
13. Divide logic-up assembly(w/buttons) from base assembly
14. Divide small PCB from base assembly
15. Remove speaker
16. Divide MB from base assembly
17. Remove MXM board from MB
18. Divide Smart card from logic upper
19. Divide T/P bracket and pcb from logic upper
20. Divide LCD cover & LCD bezel.
21. Divide LCD panel and Hinge Bracket.
22. Divide antenna cable, MIC, KB light and camera module

3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).
Step 3. Remove RAM door and RTC battery.

Step 4. Remove Blue tooth door.

Step 5. Remove HDD door.

Step 6. Remove HDD module.

Step 7. Remove ODD assembly.

Step 8. Remove Keyboard.
Step 9. Remove strip cover

Step 10-11. Remove LCD cable and antenna connector. Divide LCD assembly from base assembly

Step 12. Remove fan module

Step 13. Divide logic-up assembly (w/buttons) from base

Step 14. Divide small PCB from base assembly

Step 15. Remove speaker

Step 17. Remove MXM board from MB

Step 18. Divide Smart card from logic upper

Step 19. Divide T/P bracket and pcb from logic upper

Step 20. Divide LCD cover & LCD bezel

Step 21. Divide LCD panel and Hinge Bracket.
Step 22. Divide antenna cable, MIC, KB light and camera module